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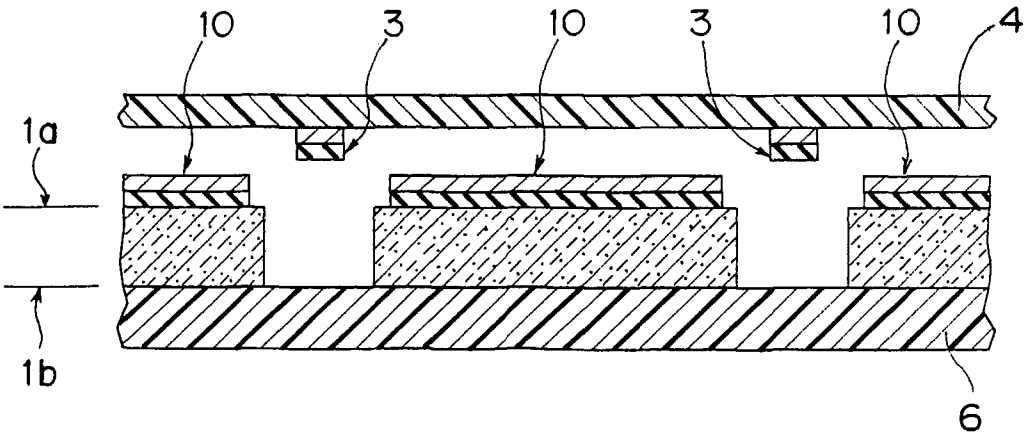
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(54) **Title:** MANUFACTURING METHOD FOR SEMICONDUCTOR CHIPS



(57) **Abstract:** The semiconductor chip manufacturing process is carried out in processes including a protective sheet sticking process for sticking a protective sheet onto a first surface of a semiconductor wafer so that the sheet comes in contact with the TEG, a mask placing process for placing a mask on a second surface that is a surface opposite from the first surface, a plasma etching process for performing plasma etching from the second surface to remove portions corresponding to dividing regions and separate device-formation-regions into individual semiconductor chips, and a TEG removing process for removing the TEG in a state where it remains unremoved in the dividing regions and stuck to the protective sheet together with the protective sheet by peeling off the protective sheet.

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